

Technical Data Sheet (TDS)

IFK-100 Refill

Wood Flooring Repair Kit

Special features

■ Fills voids under engineered or solid wood flooring



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General Features

- Contains no isocyanates
- Contains no water
- □ High shear strength
- □ Contains no chlorinated solvents
- Contains no solvents
- □ Contains no VOC (calc. per CA Rule 1168)
- Nonflammable
- High solids content
- Ozone friendly
- □ Special polymer will not etch floors finish
 □ Moisture cured for a strong bond
- Freeze/thaw stable
- □ Works under any STAUF adhesive

Installation Features

- Bridges normal sub floor variations
- Eliminates hollow spots
- Very low odor
- □ Cleans with acetone
- Does not cause cupping of wood flooring
- Higher temp and RH will shorten drying time
- No risk of sensitization

Long Term Features

- Resistant against aging
- Remains elastic
- Suitable for radiant heat systems
- □ Allows normal dimensional changes in wood flooring
- Adhesive is waterproof when cured
- Eliminates hollow spots
- No health hazards

Drying Time

■ Approx. 12 hours

Temperature Range during Installation ■ 50-90F (10-32C)

Relative Humidity Range during Installation

a 30% - 80%

Packing Size

- 1 qrt. Refill 6 count case
- □ 1 gal. Refill 6 count case

Density [lbs./gal.]

10.9

Color

□ Cream

Shelf Life

■ 6 Months in original, unopened container